

B³ 10. (Amended) The semiconductor chip according to claim 12, further comprising a lead frame and a bonding wire, the bonding wire electrically interconnecting the lead frame and the wire connecting portion.

Please add new claims 11 and 12 as follows:

B⁴ -- 11. (NEW) A semiconductor chip adapted for electrical connection to an external terminal, comprising:

a semiconductor chip body having a surface with internal wiring disposed thereon, at least one surface area of the internal wiring defining an external connection pad facing in a same direction as the surface of the semiconductor chip body;

a wire connecting portion fabricated from a metal material having oxidation resistance and electrically connected to the external connection pad;

a surface protective film covering the internal wiring and the surface of the semiconductor chip body while contacting the wire connecting portion in a surrounding manner such that a segment of the wire connecting portion projects from the surface protective film; and

a wire electrically connected to the segment of the wire connecting portion for connecting the semiconductor chip to the external terminal.

12. (NEW) A semiconductor device having a chip-on-chip structure in which a secondary chip is overlapped with and joined to a primary chip, wherein

said primary chip comprises

a primary chip body having a surface with internal wiring disposed thereon, at least one surface area of the internal wiring defining an external connection pad and at least one other surface area different from the at least one surface area of the internal wiring defining an internal connection pad, both the external connection pad and the internal connection pad facing in a same direction as the surface of the primary chip body;

a wire connecting portion fabricated from a metal material having oxidation resistance and electrically connected to the external connection pad;